

**Electrolytic Hard Gold Plating Solution and Plating Method
Using the Same**

ABSTRACT

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[Task]

To provide a gold plating solution which, in the partial plating for forming a Ni barrier layer in a connector material, can suppress the formation of gold plating film in the Ni barrier portion (an unintended

10 portion) of the connector material.

[Means for Achieving the Task]

The formation of gold plating film in Ni barrier portion can be suppressed by conducting partial plating a connector material using an electrolytic hard gold plating

15 solution containing

a gold cyanide and/ or a salt thereof,
a cobalt salt,
a conductive organic acid salt,
20 a nitro group-containing compound, and
at least one kind of compound selected from the group consisting of a carboxylic acid, an oxycarboxylic acid, and salts thereof.

[Selected Drawing]

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Fig. 1